

MC100EP139

Product Preview

÷2/4, ÷4/5/6 Clock Generation Chip

The MC100EP139 is a low skew ÷2/4, ÷4/5/6 clock generation chip designed explicitly for low skew clock generation applications. The internal dividers are synchronous to each other, therefore, the common output edges are all precisely aligned. The device can be driven by either a differential or single-ended ECL or, if positive power supplies are used, LVPECL input signals. In addition, by using the V_{BB} output, a sinusoidal source can be AC coupled into the device. If a single-ended input is to be used, the V_{BB} output should be connected to the $\overline{\text{CLK}}$ input and bypassed to ground via a 0.01μF capacitor.

The common enable ($\overline{\text{EN}}$) is synchronous so that the internal dividers will only be enabled/disabled when the internal clock is already in the LOW state. This avoids any chance of generating a runt clock pulse on the internal clock when the device is enabled/disabled as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock, therefore, all associated specification limits are referenced to the negative edge of the clock input.

Upon startup, the internal flip-flops will attain a random state; therefore, for systems which utilize multiple EP139s, the master reset (MR) input must be asserted to ensure synchronization. For systems which only use one EP139, the MR pin need not be exercised as the internal divider design ensures synchronization between the ÷2/4 and the ÷4/5/6 outputs of a single device. All V_{CC} and V_{EE} pins must be externally connected to power supply to guarantee proper operation.

- 50ps Output-to-Output Skew
- PECL mode: 3.0V to 5.5V V_{CC} with V_{EE} = 0V
- ECL mode: 0V V_{CC} with V_{EE} = -3.0V to -5.5V
- Synchronous Enable/Disable
- Master Reset for Synchronization of Multiple Chips
- Q Output will default LOW with inputs open or at V_{EE}
- ESD Protection: >2KV HBM, >100V MM
- V_{BB} Output
- New Differential Input Common Mode Range
- Moisture Sensitivity Level 2
- For Additional Information, See Application Note AND8003/D
- Flammability Rating: UL-94 code V-0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 758 devices



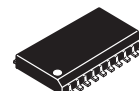
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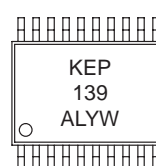


TSSOP-20
DT SUFFIX
CASE 948E

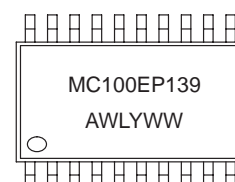


SO-20
DW SUFFIX
CASE 751D

MARKING DIAGRAM



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

*For additional information, see Application Note AND8002/D

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|---------|----------------|
| MC100EP139DT | TSSOP | 75 Units/Rail |
| MC100EP139DTR2 | TSSOP | 2500 Tape/Reel |
| MC100EP139DW | SOIC | 38 Units/Rail |
| MC100EP139DWR2 | SOIC | 2500 Tape/Reel |

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MC100EP139

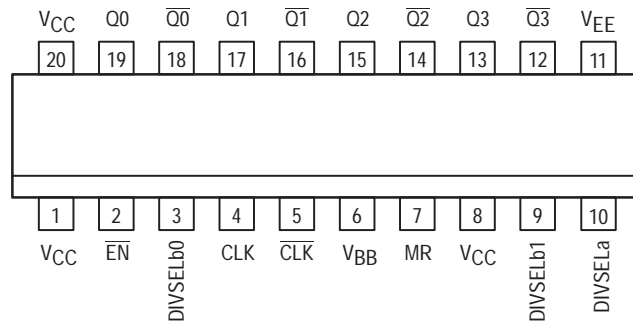


Figure 1. 20-Lead SOIC (Top View)

Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

FUNCTION TABLES

| CLK | EN | MR | FUNCTION |
|-----|----|----|------------|
| Z | L | L | Divide |
| ZZ | H | L | Hold Q0:3 |
| X | X | H | Reset Q0:3 |

Z = Low-to-High Transition
ZZ = High-to-Low Transition

| DIVSELa | Q0:1 OUTPUTS | |
|----------|--------------|--------------|
| 0 | Divide by 2 | |
| 1 | Divide by 4 | |
| DIVSELb0 | DIVSELb1 | Q2:3 OUTPUTS |
| 0 | 0 | Divide by 4 |
| 1 | 0 | Divide by 6 |
| 0 | 1 | Divide by 5 |
| 1 | 1 | Divide by 5 |

| PIN DESCRIPTION | |
|---|-------------------------------------|
| PIN | FUNCTION |
| CLK, $\overline{\text{CLK}}$ | ECL Diff Clock Inputs |
| EN | ECL Sync Enable |
| MR | ECL Master Reset |
| V _{BB} | ECL Reference Output |
| Q0, Q1, $\overline{\text{Q0}}$, $\overline{\text{Q1}}$ | ECL Diff $\div 2/4$ Outputs |
| Q2, Q3, $\overline{\text{Q2}}$, $\overline{\text{Q3}}$ | ECL Diff $\div 4/5/6$ Outputs |
| DIVSELa | ECL Freq. Select Input $\div 2/4$ |
| DIVSELb0 | ECL Freq. Select Input $\div 4/5/6$ |
| DIVSELb1 | ECL Freq. Select Input $\div 4/5/6$ |
| V _{CC} | ECL Positive Supply |
| V _{EE} | ECL Negative, 0 Supply |

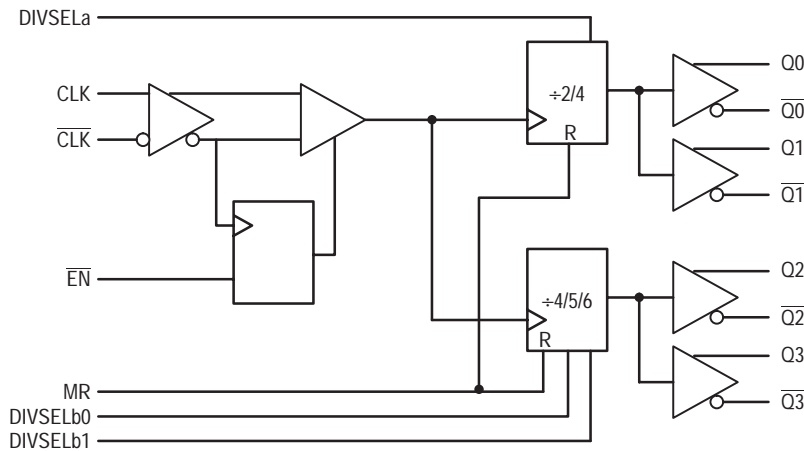


Figure 2. Logic Diagram

MC100EP139

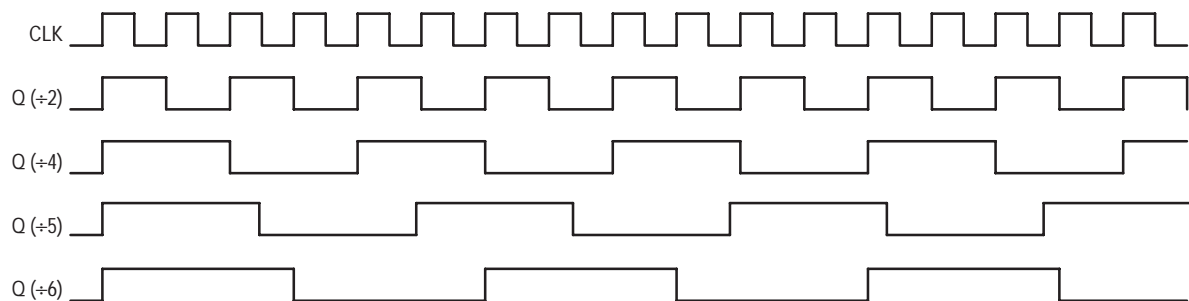


Figure 3. Timing Diagram

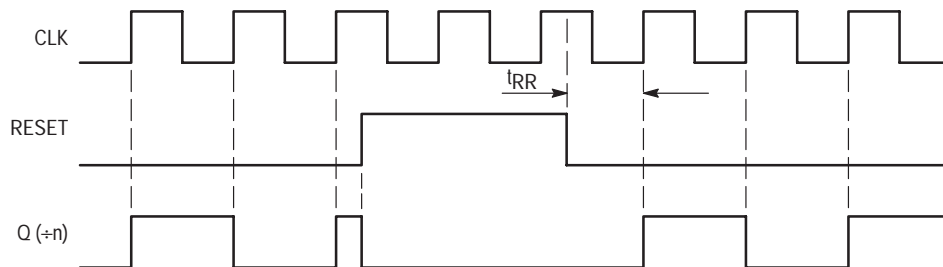


Figure 4. Timing Diagram

MAXIMUM RATINGS*

| Symbol | Parameter | Value | Unit |
|---------------------------|---|--------------------|------|
| V_{EE} | Power Supply ($V_{CC} = 0V$) | -6.0 to 0 | VDC |
| V_{CC} | Power Supply ($V_{EE} = 0V$) | 6.0 to 0 | VDC |
| V_I | Input Voltage ($V_{CC} = 0V$, V_I not more negative than V_{EE}) | -6.0 to 0 | VDC |
| V_I | Input Voltage ($V_{EE} = 0V$, V_I not more positive than V_{CC}) | 6.0 to 0 | VDC |
| I_{out} | Output Current Continuous Surge | 50 100 | mA |
| I_{BB} | V_{BB} Sink/Source Current† | ± 0.5 | mA |
| T_A | Operating Temperature Range | -40 to +85 | °C |
| T_{stg} | Storage Temperature | -65 to +150 | °C |
| θ_{JA} (DT Suffix) | Thermal Resistance (Junction-to-Ambient) Still Air 500lfpm | 140 100 | °C/W |
| θ_{JC} (DT Suffix) | Thermal Resistance (Junction-to-Case) | 23 to 41 $\pm 5\%$ | °C/W |
| θ_{JA} (DW Suffix) | Thermal Resistance (Junction-to-Ambient) Still Air 500lfpm | 90 60 | °C/W |
| θ_{JC} (DW Suffix) | Thermal Resistance (Junction-to-Case) | 33 to 35 $\pm 5\%$ | °C/W |
| T_{sol} | Solder Temperature (<2 to 3 Seconds: 245°C desired) | 265 | °C |

* Maximum Ratings are those values beyond which damage to the device may occur.

† Use for inputs of same package only.

MC100EP139

DC CHARACTERISTICS, ECL/LVECL ($V_{CC} = 0V$, $V_{EE} = -5.5V$ to $-3.0V$) (Note 3.)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-----------------|-----------------------------------|-------------|-------|-------|-------------|-------|-------|-------------|-------|-------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| IEE | Power Supply Current (Note 1.) | 70 | 85 | 100 | 70 | 90 | 105 | 75 | 95 | 110 | mA |
| V _{OH} | Output HIGH Voltage (Note 2.) | -1250 | -1100 | -895 | -1250 | -1100 | -895 | -1250 | -1100 | -895 | mV |
| V _{OL} | Output LOW Voltage (Note 2.) | -1995 | -1850 | -1650 | -1995 | -1850 | -1650 | -1995 | -1850 | -1650 | mV |
| V _{IH} | Input HIGH Voltage Single Ended | | -1022 | | | -1022 | | | -1022 | | mV |
| V _{IL} | Input LOW Voltage Single Ended | | -1642 | | | -1642 | | | -1642 | | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I _{IL} | Input LOW Current CLK CLK | 0.5 -150 | | | 0.5 -150 | | | 0.5 -150 | | | μA |

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

1. $V_{CC} = 0V$, $V_{EE} = V_{EEmin}$ to V_{EEmax} , all other pins floating.

2. All loading with 50 ohms to $V_{CC} - 2.0$ volts.

3. Input and output parameters vary 1:1 with V_{CC} .

DC CHARACTERISTICS, LVPECL ($V_{CC} = 3.3V \pm 0.3V$, $V_{EE} = 0V$) (Note 6.)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-----------------|-----------------------------------|-------------|------|------|-------------|------|------|-------------|------|------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| IEE | Power Supply Current (Note 4.) | 70 | 83 | 100 | 70 | 87 | 105 | 75 | 90 | 110 | mA |
| V _{OH} | Output HIGH Voltage (Note 5.) | 2050 | 2200 | 2405 | 2050 | 2200 | 2405 | 2050 | 2200 | 2405 | mV |
| V _{OL} | Output LOW Voltage (Note 5.) | 1305 | 1450 | 1650 | 1305 | 1450 | 1650 | 1305 | 1450 | 1650 | mV |
| V _{IH} | Input HIGH Voltage Single Ended | | 2277 | | | 2277 | | | 2277 | | mV |
| V _{IL} | Input LOW Voltage Single Ended | | 1657 | | | 1657 | | | 1657 | | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I _{IL} | Input LOW Current CLK CLK | 0.5 -150 | | | 0.5 -150 | | | 0.5 -150 | | | μA |

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

4. $V_{CC} = 3.0V$, $V_{EE} = 0V$, all other pins floating.

5. All loading with 50 ohms to $V_{CC} - 2.0$ volts.

6. Input and output parameters vary 1:1 with V_{CC} .

MC100EP139

DC CHARACTERISTICS, PECL ($V_{CC} = 5.0V \pm 0.5V$, $V_{EE} = 0V$) (Note 9.)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-----------------|-----------------------------------|-------------|------|------|-------------|------|------|-------------|------|------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| IEE | Power Supply Current (Note 7.) | 70 | 85 | 100 | 70 | 90 | 105 | 75 | 95 | 110 | mA |
| V _{OH} | Output HIGH Voltage (Note 8.) | 3750 | 3900 | 4105 | 3750 | 3900 | 4105 | 3750 | 3900 | 4105 | mV |
| V _{OL} | Output LOW Voltage (Note 8.) | 3005 | 3150 | 3350 | 3005 | 3150 | 3350 | 3005 | 3150 | 3350 | mV |
| V _{IH} | Input HIGH Voltage Single Ended | | 3977 | | | 3977 | | | 3977 | | mV |
| V _{IL} | Input LOW Voltage Single Ended | | 3357 | | | 3357 | | | 3357 | | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I _{IL} | Input LOW Current CLK CLK | 0.5 -150 | | | 0.5 -150 | | | 0.5 -150 | | | μA |

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

7. $V_{CC} = 5.0V$, $V_{EE} = 0V$, all other pins floating.

8. All loading with 50 ohms to $V_{CC} - 2.0$ volts.

9. Input and output parameters vary 1:1 with V_{CC} .

AC CHARACTERISTICS ($V_{CC} = 3.0V$ to $5.5V$; $V_{EE} = 0V$) or ($V_{CC} = 0V$; $V_{EE} = -3.0V$ to $-5.5V$)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|--|---|------------|-----|------|------------|-----------|------|------------|-----|------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f _{max} | Maximum Toggle Frequency (Note 10.) | 1.0 | 1.2 | | 1.0 | 1.2 | | 1.0 | 1.2 | | GHz |
| t _{PLH} , t _{PHL} | Propagation Delay CLK, Q(DIFF) CLK, Q(SE) MR, Q | 550 | 700 | 800 | 600 | 750 | 900 | 675 | 825 | 975 | ps |
| t _{SKEW} | Device Skew Part-to-Part (Note 11.) Q, \bar{Q} | | | | | 50 200 | | | | | ps |
| t _{JITTER} | Cycle-to-Cycle Jitter | | TBD | | | TBD | | | TBD | | ps |
| t _r t _f | Output Rise and Fall Times Q, \bar{Q} (20% – 80%) | 110 | 180 | 250 | 125 | 190 | 275 | 150 | 215 | 300 | ps |
| t _s | Setup Time \bar{EN} , \bar{CLK} DIVSEL, CLK | 200 400 | 120 | | 200 400 | 120 | | 200 400 | 120 | | ps |
| t _h | Hold Time \bar{CLK} , \bar{EN} CLK, DIVSEL | 100 150 | 50 | | 100 150 | 50 | | 100 150 | 50 | | ps |
| V _{pp} | Input Voltage Swing (Diff) | 300 | 800 | 1200 | 300 | 800 | 1200 | 300 | 800 | 1200 | mV |
| t _{rr} | Reset Recovery Time | | | | | 100 | | | | | ps |
| t _{pw} | Minimum Pulse Width CLK MR | 550 | 450 | | 550 | 450 | | 550 | 450 | | ps |

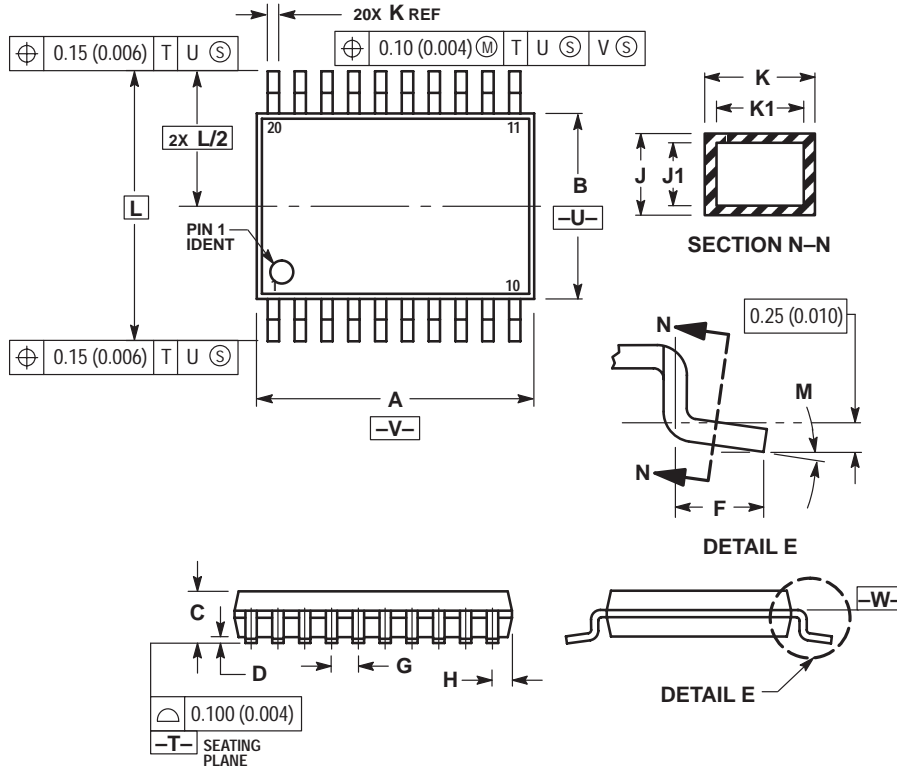
10. F_{max} guaranteed for functionality only. V_{OL} and V_{OH} levels are guaranteed at DC only.

11. Skew is measured between outputs under identical transitions.

MC100EP139

PACKAGE DIMENSIONS

TSSOP-20
DT SUFFIX
 20 PIN PLASTIC TSSOP PACKAGE
 CASE 948E-02
 ISSUE A



NOTES:

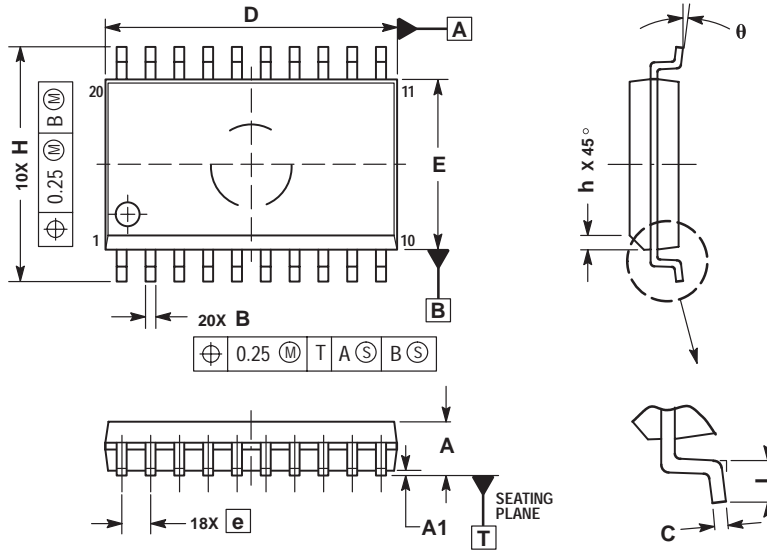
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 6.40 | 6.60 | 0.252 | 0.260 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | — | 1.20 | — | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.27 | 0.37 | 0.011 | 0.015 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

MC100EP139


PACKAGE DIMENSIONS

SO-20
DW SUFFIX
 20 PIN PLASTIC SOIC PACKAGE
 CASE 751D-05
 ISSUE F



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | |
|-----|-------------|-------|
| | MIN | MAX |
| A | 2.35 | 2.65 |
| A1 | 0.10 | 0.25 |
| B | 0.35 | 0.49 |
| C | 0.23 | 0.32 |
| D | 12.65 | 12.95 |
| E | 7.40 | 7.60 |
| e | 1.27 BSC | |
| H | 10.05 | 10.55 |
| h | 0.25 | 0.75 |
| L | 0.50 | 0.90 |
| θ | 0° | 7° |

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